



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q66510

Toshio SHINTANI, et al.

Appln. No.: 09/974,048

Confirmation No.: 7616

Group Art Unit: 2827

Filed: October 11, 2001

Examiner: Tuan T. DINH

For: CIRCUIT BOARD AND CONNECTION STRUCTURE OF TERMINAL PORTION OF
THE SAME

PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Prior to examination, please amend the above-identified application as follows:

IN THE CLAIMS:

1. (Previously Amended) A circuit board comprising:

a terminal portion connected with an external terminal formed in an external circuit, said terminal portion provided with a nickel plating layer and a soldering bump;
wherein a thickness of said nickel plating layer is within a range of 1.0 to 4.0 μm ,
wherein said terminal portion further includes a base layer, and a conductive layer disposed between said base layer and said nickel plating layer, wherein a thickness of said base layer comprises polyimide resin,
wherein said soldering bump contains tin and at least one of silver and copper.